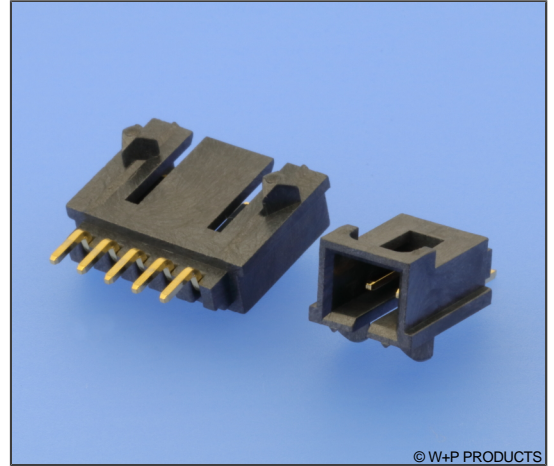


## SMT Crimp-Rast-Stiftleisten RM 2,54mm, liegend SMT Friction Lock Headers, 2.54mm Pitch, Horizontal

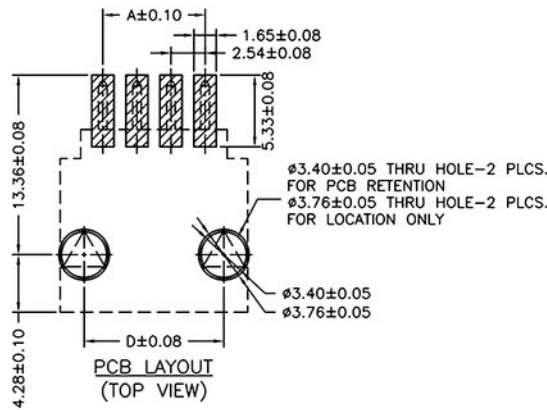
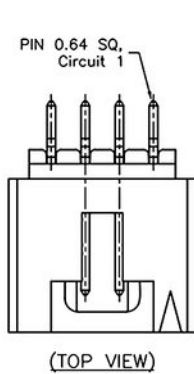
### Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Vierkantstift 0,64mm, Kupferlegierung <i>0.64mm square pin, copper alloy</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	1500 V AC
Nennspannung <i>Voltage Rating</i>	250 V AC
Nennstrom <i>Current Rating</i>	3 A
Temperaturbereich <i>Temperature Range</i>	-25 °C ... +85 °C
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>

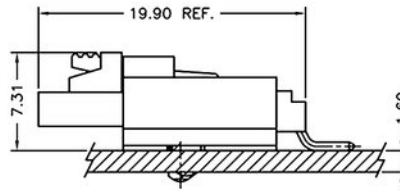
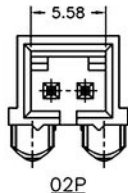
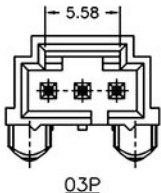
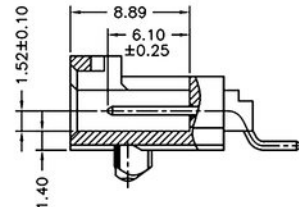
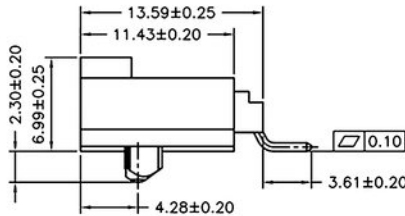
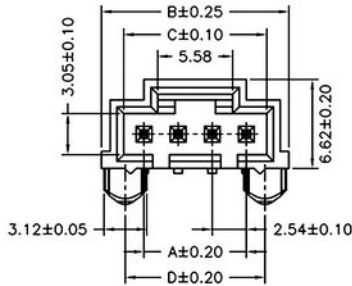


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Gegenstecker / Mating connectors: 532



Circuit No.	Dimensions			
	A	B	C	D
02P	2.54	8.89	---	5.33
03P	5.08	11.43	8.12	7.87
04P	7.62	13.97	10.66	10.41
05P	10.16	16.51	13.20	12.95
06P	12.70	19.05	15.74	15.49
07P	15.24	21.59	18.28	18.03
08P	17.78	24.13	20.82	20.57
09P	20.32	26.67	23.36	23.11
10P	22.86	29.21	25.90	25.65
11P	25.40	31.75	28.44	28.19
12P	27.94	34.29	30.98	30.73



Series

**5320**

Contacts\*

**04**

02-12

Type

**4**

4 Stiftleiste liegend  
Horizontal pin header

Plating

**00**

00 Vergoldet  
Gold plated

\* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** - please replace by your specifications.

# Informationen zum Reflow-Lötverfahren

## Reflow Soldering Information

### Reflow-Lötempfehlung

#### Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Lötten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150 °C
Temperatur Maximum $T_{Smax}$	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich $T_L$	217 °C
Verweildauer oberhalb $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur $T_P$	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur $T_P$	max. 8m

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150 °C
Maximum Temperatur $T_{Smax}$	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature $T_L$	217 °C
Duration above $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature $T_P$	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. $T_P$	max. 8min

